CLEANING SOLUTION USED IN PROCESS OF FABRICATING SEMICONDUCTOR DEVICE

ABSTRACT OF THE DISCLOSURE

A cleaning solution used in processes of fabricating semiconductor devices is disclosed. The cleaning solution includes deionized water and a surfactant represented by the following formula:

$$R_1 + O \longrightarrow_n OH$$
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wherein R_1 and R_3 are carbides or fluorocarbons having 1 to 20 carbons, R_2 is hydrogen or carbide, m+p is an integer from 1 to 30, n+q is an integer from 0 to 10, and the surfactant is about 0.01 to about 1.0 wt.% based on the total weight of the deionized water.